

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No. 09/546,174	Confirmation No.: 4793
Application of: Chih-Chien Liu, Ta-Shan Tseng, W. B. Shieh, J. Y. Wu, Water Lur and Shih-Wei Sun	Customer No.: <b>25235</b>
Filed: April 11, 2000	
Art Unit: 1711	
Examiner: Sergeant, Rabon A.	
Attorney Docket No. UMC-96-279 CON	
For: HIGH DENSITY PLASMA CHEMICAL VAPOR DEPOSITION PROCESS	

AMENDMENT AND RESPONSE PURSUANT TO OFFICE ACTION DATED  
FEBRUARY 22, 2006

MAIL STOP Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the office communication mailed February 22, 2006,  
please amend the above-identified application as follows:

**Amendments to the Claims** are reflected in the listing of claims which  
begins on page 2 of this paper.

**Remarks/Arguments** begin on page 11 of this paper.

**Petition for One Month Extension of Time** with \$120 fee is attached  
following page 13 of this paper.